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PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62		
Case-to-Sink, Flat, Greased Surface	R <sub>thCS</sub>	0.50	-	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	1.0		

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		•					<b>I</b>
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 250 \mu A$		60	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.070	-	V/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$		1.0	-	2.0	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = 10 V		-	-	± 100	nA
	1	$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$ $V_{DS} = 48 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 150 ^{\circ}\text{C}$		-	-	25	μA
Zero Gate Voltage Drain Current	IDSS			-	-	250	
	R <sub>DS(on)</sub>	$V_{GS} = 5.0 V$	I <sub>D</sub> = 31 A <sup>b</sup>	-	-	0.028	Ω
Drain-Source On-State Resistance		$V_{GS} = 4.0 V$	I <sub>D</sub> = 25 A <sup>b</sup>	-	-	0.039	
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> = 25 V, I <sub>D</sub> = 31 A <sup>b</sup>		23	-	-	S
Dynamic							•
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 V,$ $V_{DS} = 25 V,$ f = 1.0 MHz, see fig. 5		-	3300	-	pF
Output Capacitance	C <sub>oss</sub>			-	1200	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	200	-	
Total Gate Charge	Qg			-	-	66	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = 5.0 V	$V_{GS} = 5.0 V$ $I_D = 51 A, V_{DS} = 48 V,$ see fig. 6 and 13 <sup>b</sup>		-	12	
Gate-Drain Charge	Q <sub>gd</sub>	see lig. 6 and 15°		-	-	43	
Turn-On Delay Time	t <sub>d(on)</sub>			-	17	-	- ns
Rise Time	t <sub>r</sub>	- V 3			230	-	
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{DD} = 30 \text{ V}, \text{ I}_{D} = 51 \text{ A}, \\ \text{R}_{g} = 4.6 \ \Omega, \text{ R}_{D} = 0.56 \ \Omega, \text{ see fig. } 10^{b}$		-	42	-	
Fall Time	t <sub>f</sub>			-	110	-	
Internal Drain Inductance	L <sub>D</sub>	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH
Internal Source Inductance	L <sub>S</sub>			-	7.5	-	
Drain-Source Body Diode Characteristic	s	•					<b>I</b>
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode $T_J = 25 \text{ °C}, I_S = 51 \text{ A}, V_{GS} = 0 \text{ V}^{b}$		-	-	50°	
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>			-	-	200	A
Body Diode Voltage	V <sub>SD</sub>			-	-	2.5	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	T 05 00 1		-	130	180	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	− T <sub>J</sub> = 25 °C, I <sub>F</sub> = 51 A, dl/dt = 100 A/μs <sup>b</sup>		-	0.84	1.3	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is			minated b	v Ls and	Ln)

#### Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. Pulse width  $\leq$  300 µs; duty cycle  $\leq$  2 %.

c. Current limited by the package, (die current = 51 A).

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#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

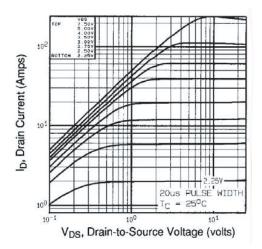


Fig. 1 - Typical Output Characteristics,  $T_C = 25 \ ^\circ C$ 

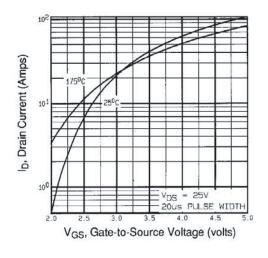


Fig. 3 - Typical Transfer Characteristics

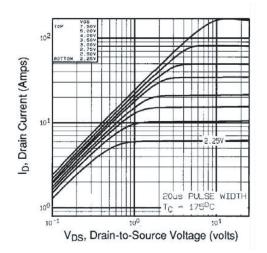


Fig. 2 - Typical Output Characteristics,  $T_C$  = 175 °C

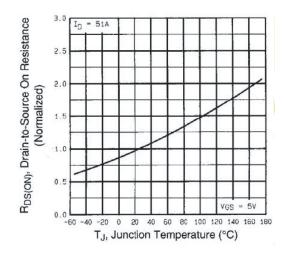


Fig. 4 - Normalized On-Resistance vs. Temperature

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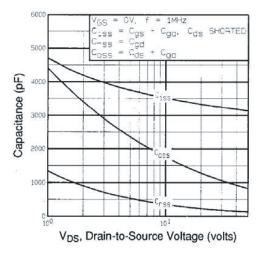


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

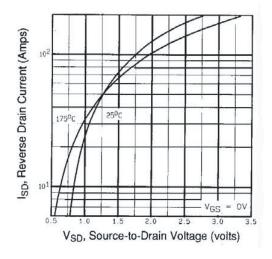


Fig. 7 - Typical Source-Drain Diode Forward Voltage

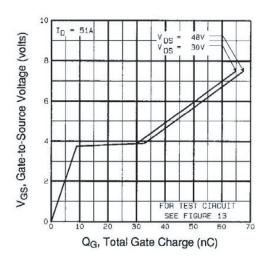


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

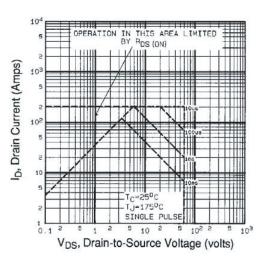


Fig. 8 - Maximum Safe Operating Area

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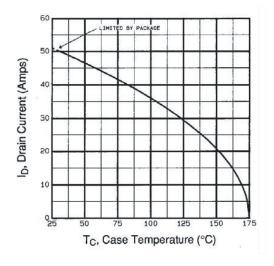


Fig. 9 - Maximum Drain Current vs. Case Temperature

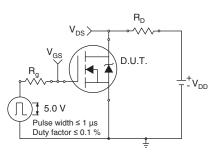


Fig. 10a - Switching Time Test Circuit

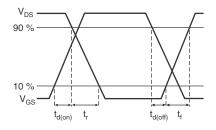


Fig. 10b - Switching Time Waveforms

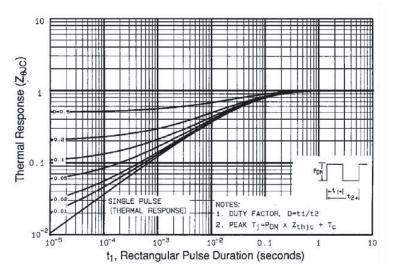


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

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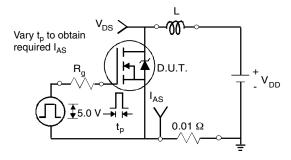


Fig. 12a - Unclamped Inductive Test Circuit

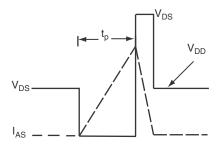


Fig. 12b - Unclamped Inductive Waveforms

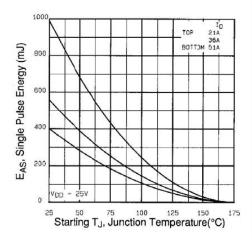
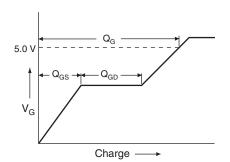


Fig. 12c - Maximum Avalanche Energy vs. Drain Current





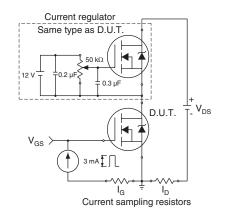


Fig. 13b - Gate Charge Test Circuit

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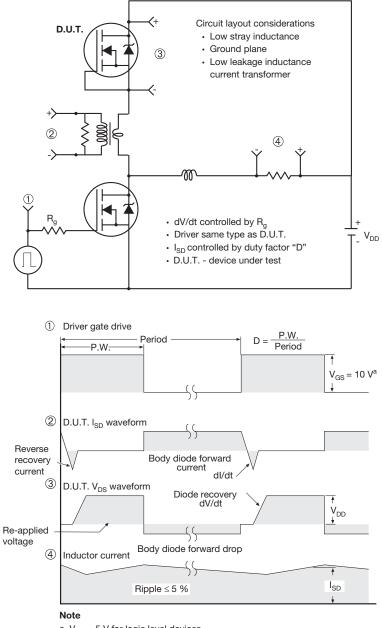
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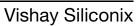
a.  $V_{GS}$  = 5 V for logic level devices

Fig. 14 - For N-Channel

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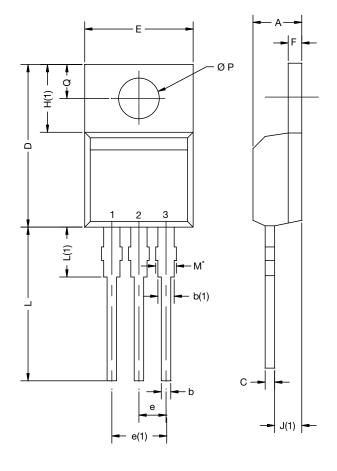
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TO-220-1



DIM.	MILLIMETERS		INCHES	
Dilvi.	MIN.	MAX.	MIN.	MAX.
А	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØР	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031				

Note

-  $M^{\star}$  = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

Package Picture					
ASE		Xi'an			
EGNEOA 7KAB 193 Co A		IRF 9510 744K AB 25 (C) (A)			

Revison: 14-Dec-15

Document Number: 66542

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